# Monthly LabAdviser/Process2Share update: 3/11 2015

|  |  |  |
| --- | --- | --- |
| Updated Subject  | Contributor | Link to the updated pages |
| **XPS**XPS data processingInformation on:* Avantage software installation
* XPS knowledge view

And subpages on analysing XPS data:Information on: * Open data, spectrum views, depth profile, survey spectrum peak identification
* Open high resolution spectra, add background and peaks, apply constraints to fitting
 | **Jonas Michael-Lindhard @danchip****Evgeniy Shkondin @danchip/photonics** | [XPS/Processing](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/XPS/Processing)[XPS/Processing/Basics](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/XPS/Processing/Basics) |
| **Several deposition pages**Deposition of MgBDeposition of AlN | **Patama Pholprasit****@danchip****Mikkel Vilsbøll Larsen and Døgg Durhuus @ Nanotec**h | [Deposition\_of\_MgB](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_MgB)[Deposition\_of\_Aluminium\_Nitride](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Aluminium_Nitride)[AlN\_in\_PVD\_co-sputter](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Aluminium_Nitride/AlN_in_PVD_co-sputter#AlN_reactive_sputtering)[AlN\_in\_PVD\_co-sputter/Setting\_4](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Deposition_of_Aluminium_Nitride/AlN_in_PVD_co-sputter/Setting_4) |
| **LPCVD poly**Boron-doped poly-Si and a-Si | **Thomas Pedersen @Nanotech** | [Boron\_doped\_poly-Si\_and\_a-Si](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Thin_film_deposition/Furnace_LPCVD_PolySilicon/Boron_doped_poly-Si_and_a-Si) |
| **AOE:** SiO2 etch with DUV mask using standard SiO2 etch (SiO2\_res) Si3N4 etch with DUV mask using standard SiO2 etch (SiO2\_res) | **Berit Herstrøm @danchip** | [SiO2\_etch\_using\_AOE/SiO2\_etch\_with\_DUV\_mask](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/Etching_of_Silicon_Oxide/SiO2_etch_using_AOE/SiO2_etch_with_DUV_mask)[Silicon\_Nitride\_Etch\_using\_AOE/Nitride\_etch\_with\_DUV\_mask](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Etch/AOE_%28Advanced_Oxide_Etch%29/Silicon_Nitride_Etch_using_AOE/Nitride_etch_with_DUV_mask) |
| **TEM (at CEN)**Equipment page of the Tecnai TEM has been made | **Wilhellmus Huyzer @CEN** | [Characterization/Tecnai\_TEM](http://labadviser.danchip.dtu.dk/index.php/Specific_Process_Knowledge/Characterization/Tecnai_TEM) |

# Equipment Manuals updated in LabManager:

As an approved user on a piece of equipment you have to make sure you have read and understood the latest version of the manual before using the equipment.

|  |
| --- |
|  |

|  |
| --- |
|  |

|  |
| --- |
|  |
|  | **Manual for Spray coater** |
|  | **Manual for Balzers sputter coater** |
|  | **Manual for Ball wire-bonder** |
|  | **Manual for SEM LEO EBL** |

|  |
| --- |
|  |